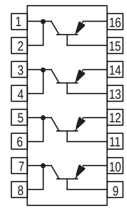
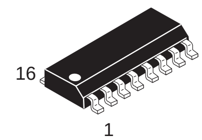
Quad Amplifier/Switch Transistor

PNP Silicon



MMPQ3906

Motorola Preferred Device



CASE 751B–05, STYLE 4
SO–16

MAXIMUM RATINGS

Rating	Symbol	Value		Unit
Collector–Emitter Voltage	V_{CEO}	–40		Vdc
Collector–Base Voltage	V_{CB}	–40		Vdc
Emitter–Base Voltage	V_{EB}	–5.0		Vdc
Collector Current — Continuous	I_C	–200		mAdc
		Each Transistor	**Four Transistors Equal Power**	
Power Dissipation @ T_A = 25°C Derate above 25°C	P_D	0.4 3.2	800 6.4	mW mW/°C
Power Dissipation @ T_C = 25°C Derate above 25°C	P_D	0.66 5.3	1.92 15.4	Watts mW/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	–55 to +150		°C

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage(1) (I_C = –1.0 mAdc, I_B = 0)	$V_{(BR)CEO}$	–40	—	—	Vdc
Collector–Base Breakdown Voltage (I_C = –10 μAdc, I_E = 0)	$V_{(BR)CBO}$	–40	—	—	Vdc
Emitter–Base Breakdown Voltage (I_E = –10 μAdc, I_C = 0)	$V_{(BR)EBO}$	–5.0	—	—	Vdc
Collector Cutoff Current (V_{CB} = –30 Vdc, I_E = 0)	I_{CBO}	—	—	–50	nAdc
Emitter Cutoff Current (V_{EB} = –4.0 Vdc, I_C = 0)	I_{EBO}	—	—	–50	nAdc

1. Pulse Test: Pulse Width ≤ 300 μs; Duty Cycle ≤ 2.0%.

Preferred devices are Motorola recommended choices for future use and best overall value.

Thermal Clad is a trademark of the Bergquist Company

REV 1

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Continued)

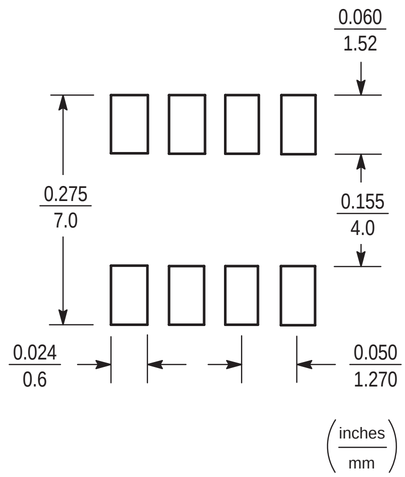
Characteristic	Symbol	Min	Typ	Max	Unit
ON CHARACTERISTICS[1]					
DC Current Gain	h_{FE}				—
(I_C = –0.1 mAdc, V_{CE} = –1.0 Vdc)		40	160	—	
(I_C = –1.0 mAdc, V_{CE} = –1.0 Vdc)		60	180	—	
(I_C = –10 mAdc, V_{CE} = –1.0 Vdc)		75	200	—	
Collector–Emitter Saturation Voltage (I_C = –10 mAdc, I_B = –1.0 mAdc)	$V_{CE(sat)}$	—	–0.1	–0.25	Vdc
Base–Emitter Saturation Voltage (I_C = –10 mAdc, I_B = –1.0 mAdc)	$V_{BE(sat)}$	—	–0.65	–0.85	Vdc
DYNAMIC CHARACTERISTICS					
Current–Gain — Bandwidth Product (I_C = –10 mAdc, V_{CE} = –20 Vdc, f = 100 MHz)	f_T	200	250	—	MHz
Output Capacitance (V_{CB} = –5.0 Vdc, I_E = 0, f = 1.0 MHz)	C_{ob}	—	3.3	4.5	pF
Input Capacitance (V_{EB} = –0.5 Vdc, I_C = 0, f = 1.0 MHz)	C_{ib}	—	4.8	10	pF
SWITCHING CHARACTERISTICS					
Turn–On Time (I_C = –10 mAdc, $V_{BE(off)}$ = 0.5 Vdc, I_{B1} = –1.0 mAdc)	t_{on}	—	43	—	ns
Turn–Off Time (I_C = –10 mAdc, I_{B1} = I_{B2} = –1.0 mAdc)	t_{off}	—	155	—	ns

1. Pulse Test: Pulse Width ≤ 300 µs; Duty Cycle ≤ 2.0%.

INFORMATION FOR USING THE SO–16 SURFACE MOUNT PACKAGE

MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



SO–16

SO–16 POWER DISSIPATION

The power dissipation of the SO–16 is a function of the pad size. This can vary from the minimum pad size for soldering to a pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by $T_{J(max)}$, the maximum rated junction temperature of the die, $R_{\theta JA}$, the thermal resistance from the device junction to ambient, and the operating temperature, T_A. Using the values provided on the data sheet for the SO–16 package, P_D can be calculated as follows:

$$P_D = \frac{T_{J(max)} - T_A}{R_{\theta JA}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values into the equation for an ambient temperature T_A of 25°C, one can calculate the power dissipation of the device which in this case is 800 milliwatts.

$$P_D = \frac{150°C - 25°C}{156°C/W} = 800 \text{ milliwatts}$$

The 156°C/W for the SO–16 package assumes the use of the recommended footprint on a glass epoxy printed circuit board to achieve a power dissipation of 800 milliwatts. There are other alternatives to achieving higher power dissipation from the SO–16 package. Another alternative would be to use a ceramic substrate or an aluminum core board such as Thermal Clad™. Using a board material such as Thermal Clad, an aluminum core board, the power dissipation can be doubled using the same footprint.

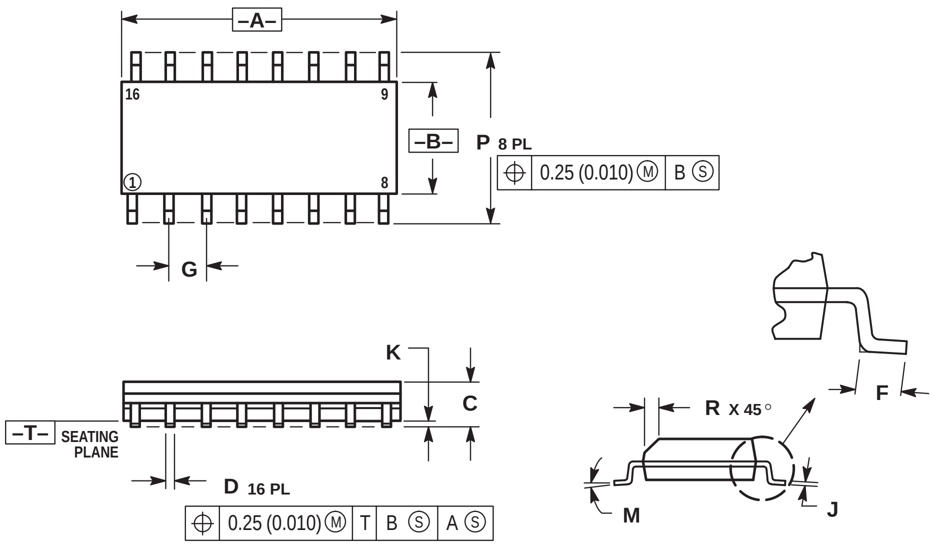
SOLDERING PRECAUTIONS

The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference shall be a maximum of 10°C.
- The soldering temperature and time shall not exceed 260°C for more than 10 seconds.
- When shifting from preheating to soldering, the maximum temperature gradient shall be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes. Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling.

* Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.

PACKAGE DIMENSIONS



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 4:
PIN 1. COLLECTOR, DYE #1
2. COLLECTOR, #1
3. COLLECTOR, #2
4. COLLECTOR, #2
5. COLLECTOR, #3
6. COLLECTOR, #3
7. COLLECTOR, #4
8. COLLECTOR, #4
9. BASE, #4
10. EMITTER, #4
11. BASE, #3
12. EMITTER, #3
13. BASE, #2
14. EMITTER, #2
15. BASE, #1
16. EMITTER, #1

CASE 751B–05
SO–16
ISSUE J

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